



M.Tech Digital Manufacturing

BITS Pilani
Pilani Campus

Jayakrishnan J Guest Faculty

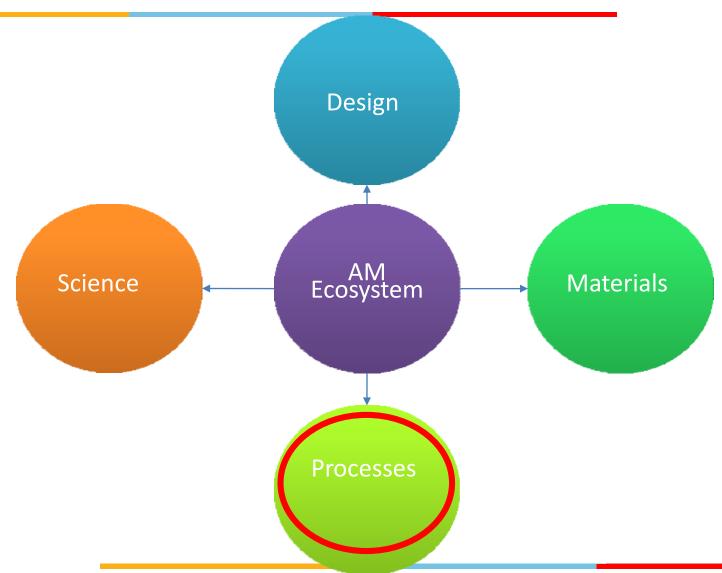




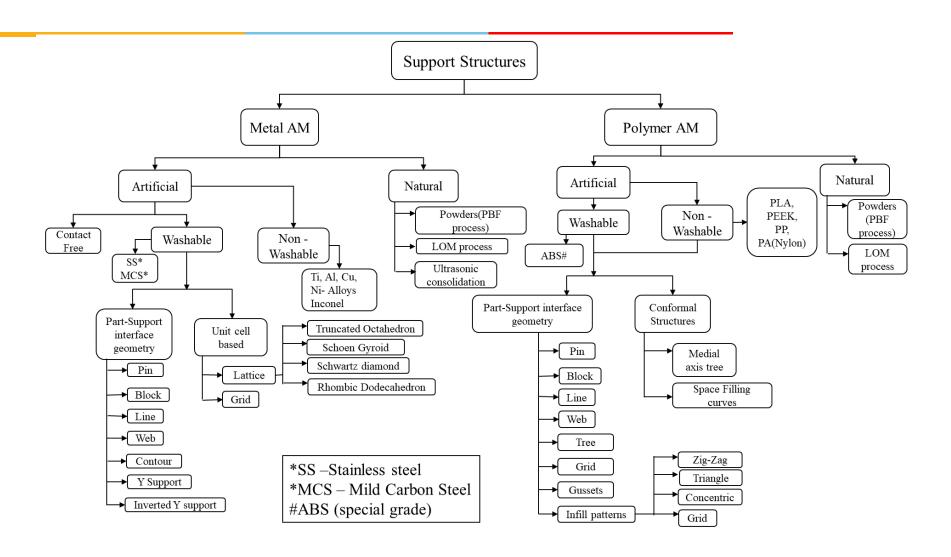
DMZG521- Design for Additive Manufacturing Session 2 & Lecture 3-4

Additive Manufacturing Ecosystem

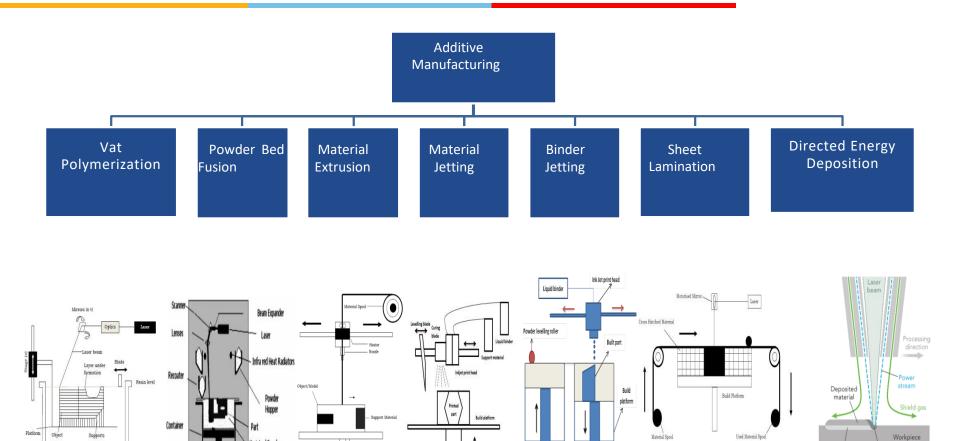




Support Structures in AM



ASTM Classification

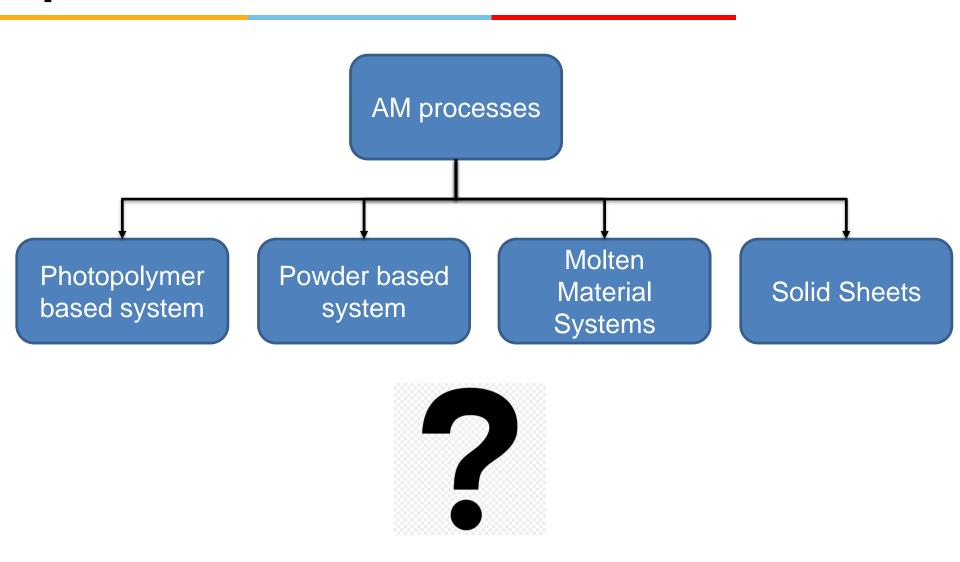


Melt pool

Dilution area

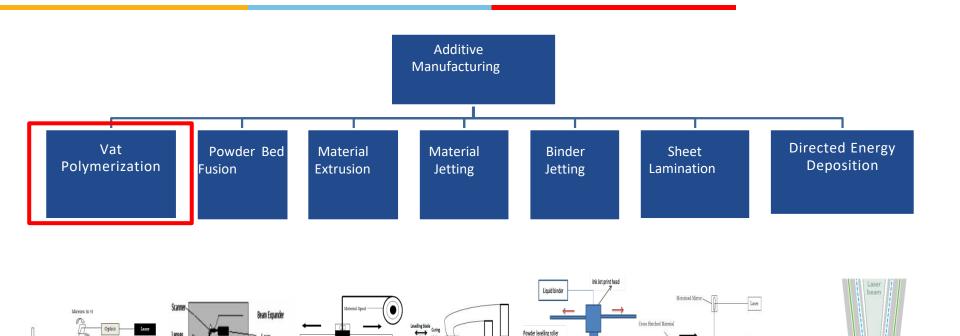
General classification of AM processes





ASTM Classification

Infra red Heat Radiators



Deposited

Dilution area

Workpiece

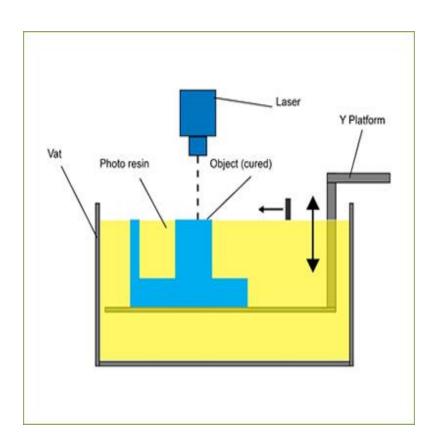
Melt pool

Used Material Spoo

Vat photopolymerization process



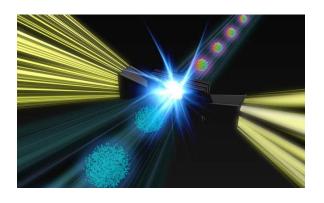
- Makes use of liquid polymers which are cured by laser radiation or UV light
- Chemical reaction from monomers to cross linked or linear chain polymerization
- Used in various industries since 1960
- Generally in coating, dentistry and printing industry



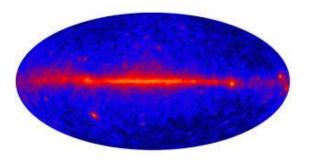


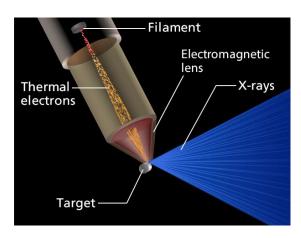
Types of Energy Sources

- Gamma Rays
- X-Rays
- Electron beam
- UV
- Visible light



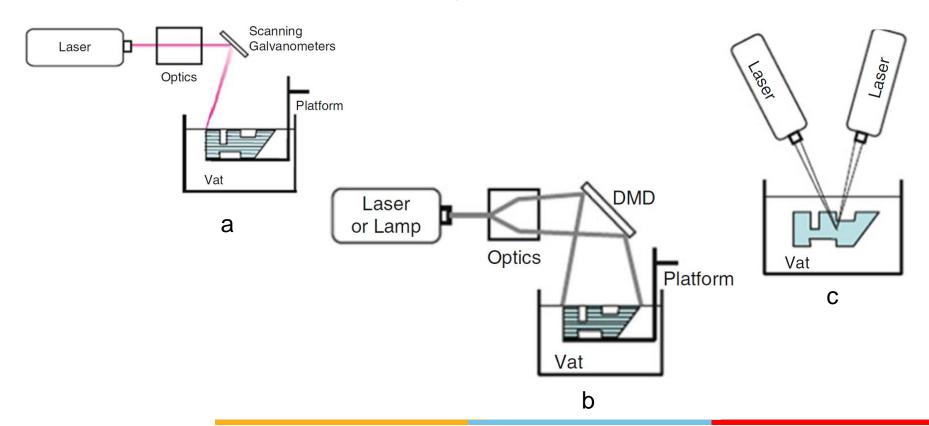






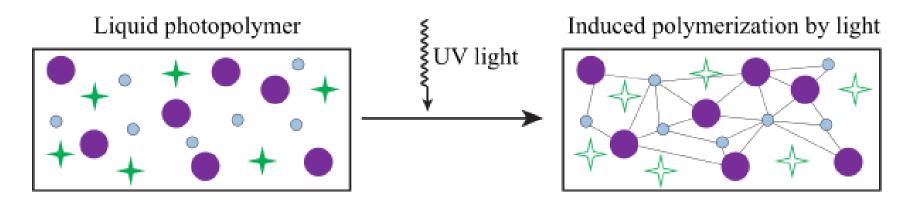
Processing Steps

- a) Vector Scan(point-wise)
- b) Mask Projection (layer wise)
- c) Two-photon approach (high resolution point to point)





Photopolymerization



- Monomer
- Oligomer
- Photoinitiator

Materials used

Acrylates

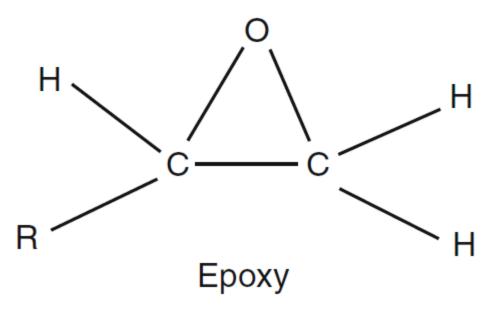
- High Reactivity
- Weak parts
- Partial curing up to 46%

Prone to shrinkage and curling
 C
 Acrylate

Materials

Epoxy based

- Slow photo speed
- Brittleness after curing
- Sensitive to humidity



Materials

Acrylate +epoxides Resins

- Combination of both these resins overcome the weaknesses displayed by the polymers
- Increased hardness
- Less susceptible to atmospheric oxygen and humidity
- Improved accuracy and part build
- Enhanced build quality and part conformance

Common SLA Materials

innovate achieve lead

- Standard and clear resins
- Engineering SLA resins
 - Tough resin(ABS-Like)
 - Durable resin(PP-Like)
 - Heat resistant resin
 - Flexible resin
 - Ceramic filled resin(Rigid)







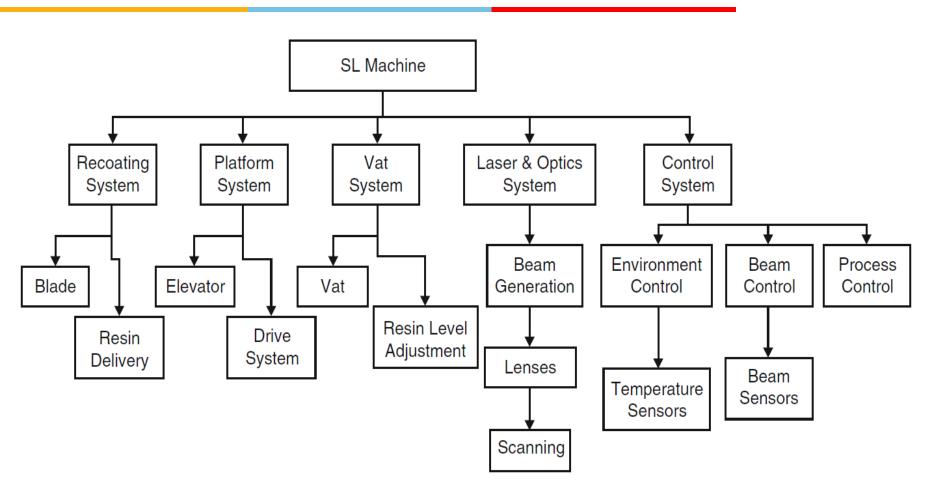




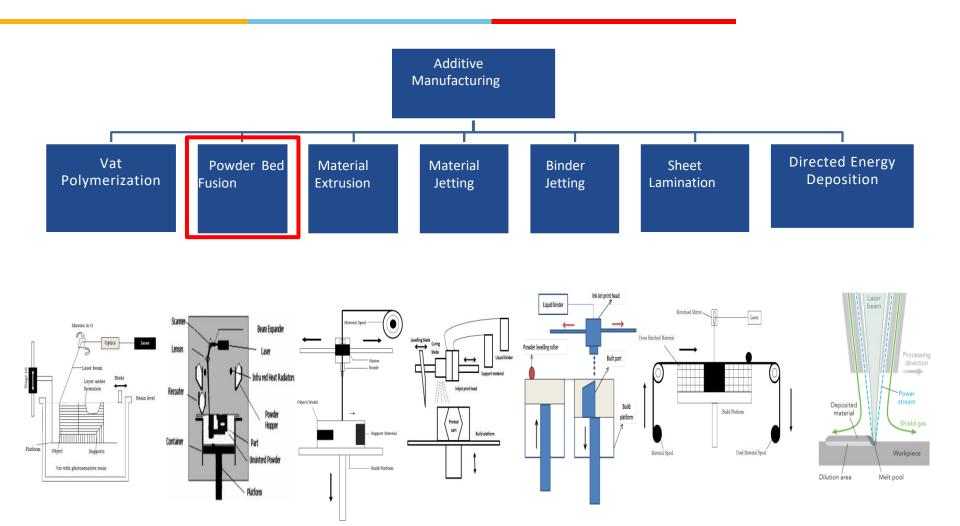


Subsystems for SL technology



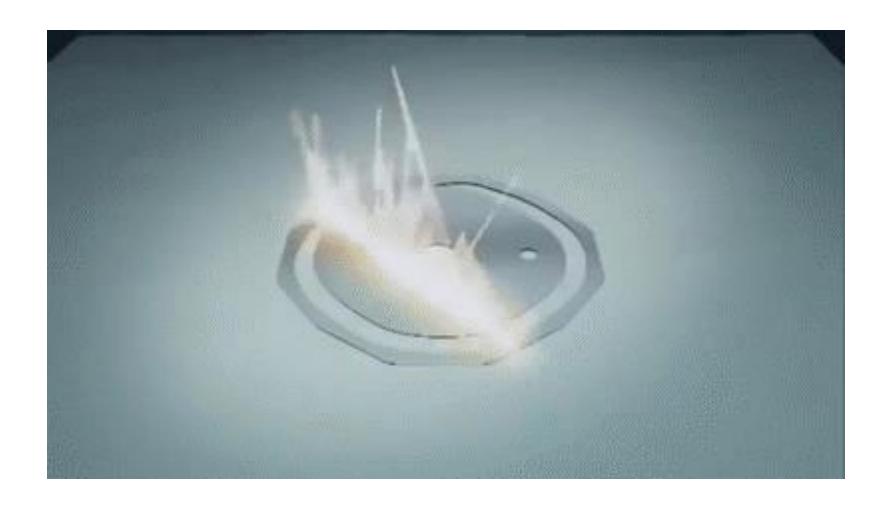


ASTM Classification

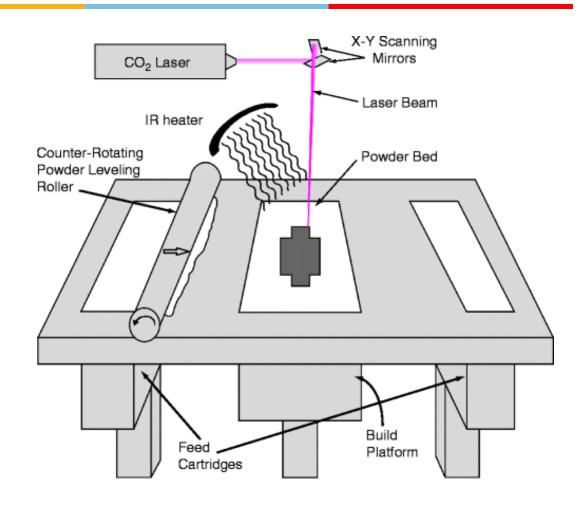




Powder Bed Fusion



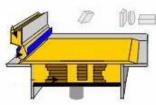
PBF Schematic



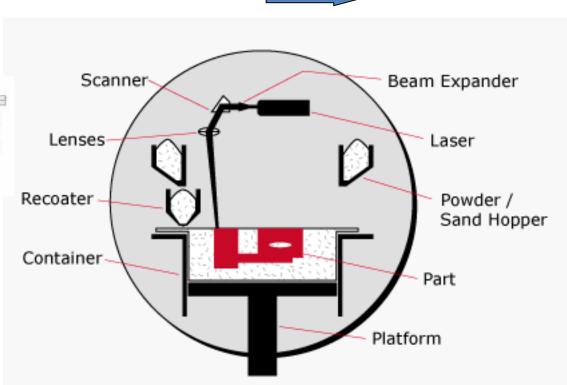


Schematic and operation of SLS machine

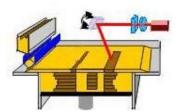
Powder spreading by recoater



Recoating for next layer

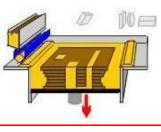


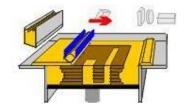
Powder bed exposed to laser beam





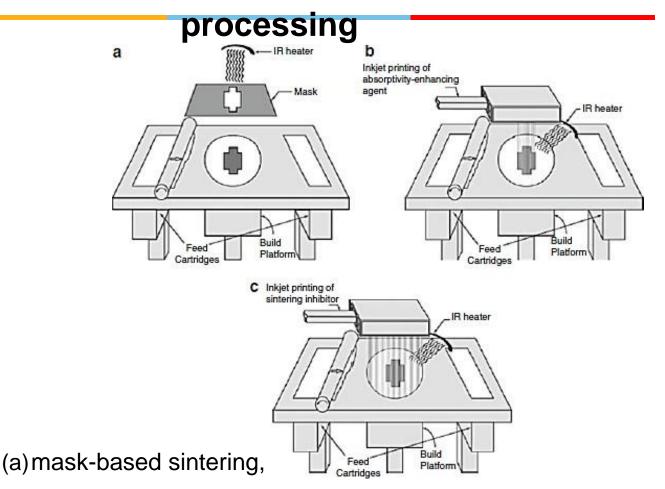
Platform moves downward





Three different approaches to line and layer- wise powder bed fusion





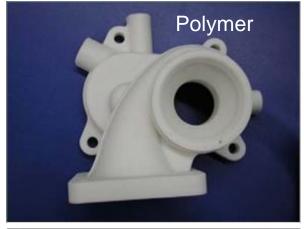
(b) printing of an absorptivity-enhancing agent in the part region,(c) printing of a sintering inhibitor outside the part region

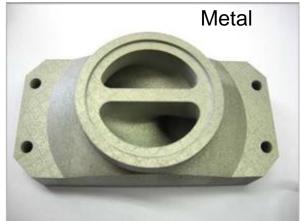
Plastics

- Selective Lase Sintering (SLS)
- Multi Jet Fusion (MJF)

Metals

- Direct Metal Laser Sintering (DMLS)
- Selective Laser Melting (SLM)
- Electron Beam Melting (EBM)





PBF Example Materials

Plastics

- Nylon 11
- Nylon 12
- Al-filled Nylon
- Fire Retardant Nylon-12
- Glass Filled Nylon

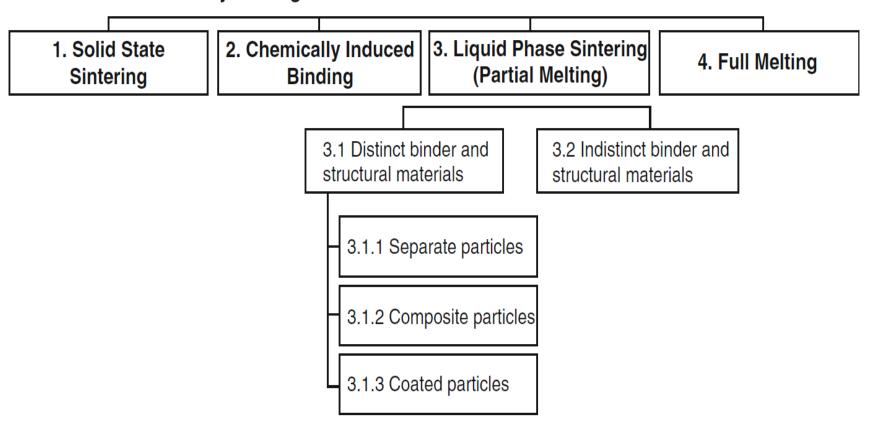
Metals

- Al alloys
- Co-Cr
- Nickel alloy (Inconel 625, Inconel 718)
- Stainless steel (316,316L, 15-5,17-4)
- Maraging steel (MS1)
- Hastalloy X
- Ti and Ti- Alloy
- Tool Steel



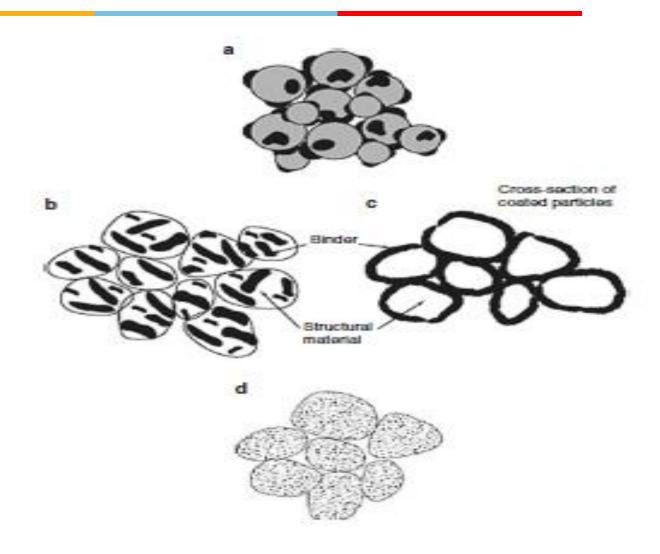
Binding Mechanism

Primary Binding Mechanisms in Powder Bed Fusion Processes



LPS or Partial Melting Particles

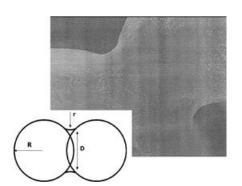




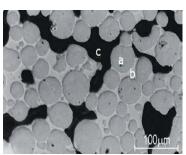


Binding Mechanism

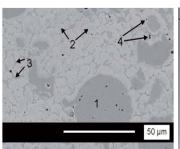
Solid State Sintering

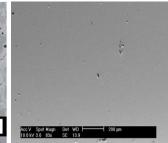


Liquid Phase Sintering

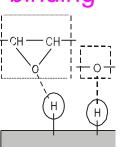


Partial Melting Full Melting

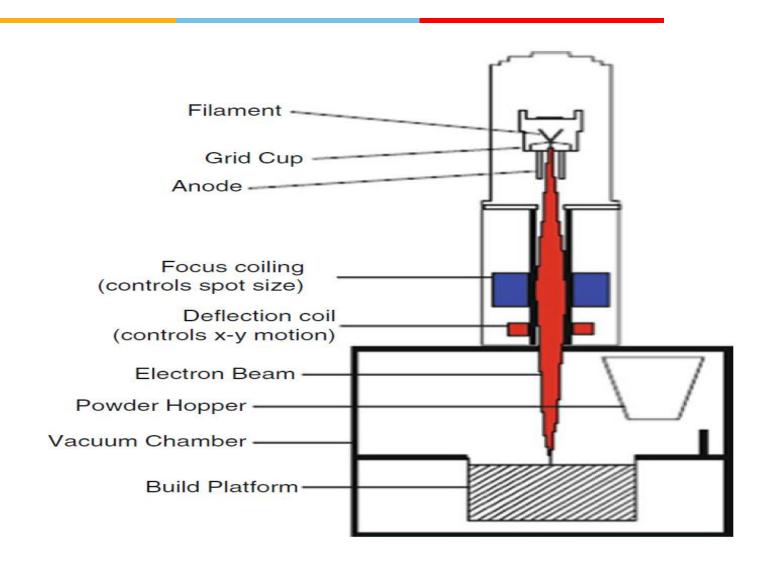




Chemical binding



EBM Schematic

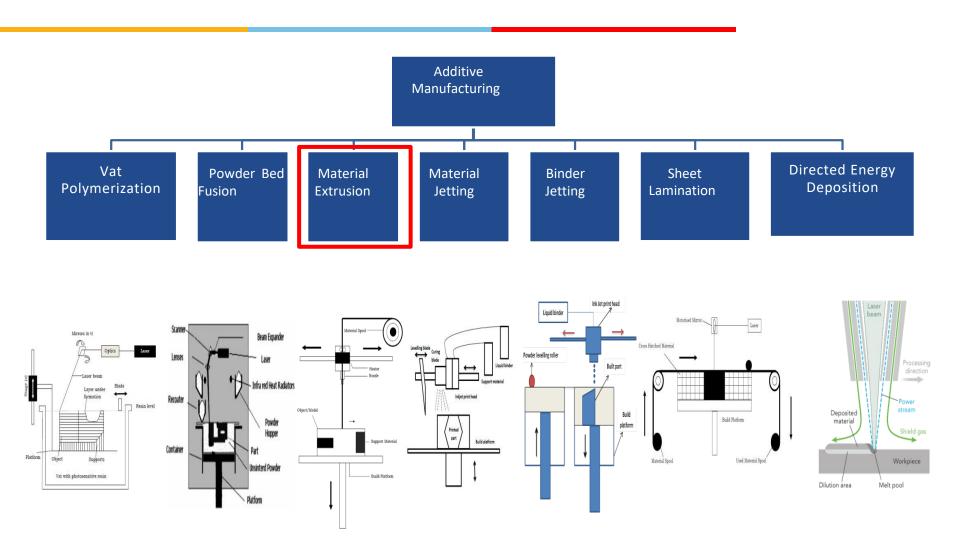




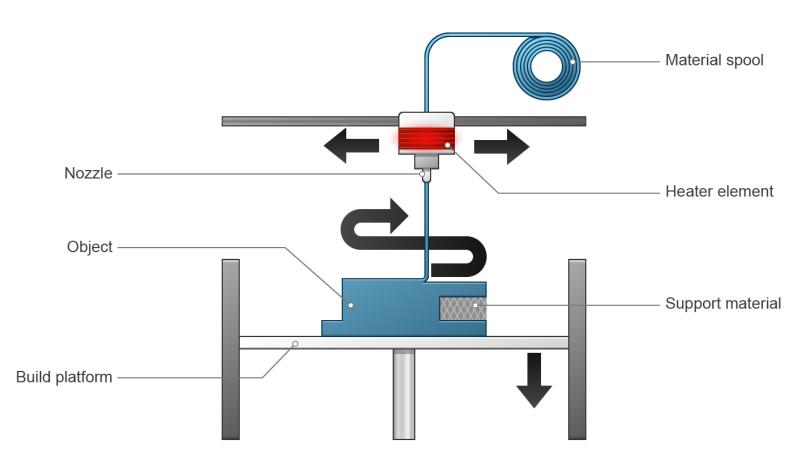
Two different Thermal sources

| Characteristics | Electron Beam Melting | Laser Melting |
|--------------------|--------------------------------|-------------------------------|
| Thermal Source | Electron Beam | Lase |
| Atmosphere | Vacuum | Inert Gas |
| Scanning | Deflection coils | Galvano scanners |
| Energy absorption | Conductivity-limited | Absorptivity-limited |
| Powder preheating | Electron beam | IR or resistive heaters |
| Scan speeds | Very fast, Magnetically driven | Limited by galvano scanners |
| Energy Cost | Moderate | High |
| Surface Finish | Moderate to poor | Excellent to moderate |
| Feature Resolution | Moderate | Excellent |
| Materials | Metals(Conductors) | Polymers, Metals and Ceramics |
| Powder Size | Medium | Fine |

ASTM Classification



Material Extrusion



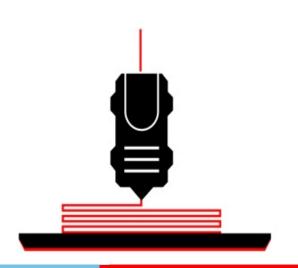
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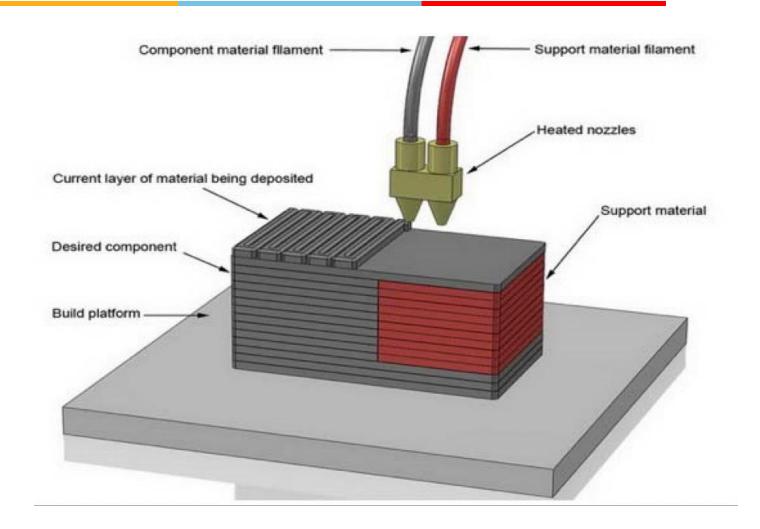
Fused Deposition Modelling

- Name given by Scott Crump
- First commercialized by Stratasys
- Most popular processes for hobbyist grade 3D printing





Dual Extruders



Materials



- Thermoplastics
 - ABS
 - PLA
 - TPU
 - PETG
 - PEEK

- Solvable supports
 - PVA(In water)
 - HIPS(In Limonene)





Source: https://www.allthat3d.com/3d-printer-filament/

Advantages

- Low initial and running costs
- Comparable faster print time for small and thin parts
- Printing tolerance of +/- 0.1 (+/- 0.005")
- No supervision required
- Small equipment size compared to other AM
- Comparably low-temperature process

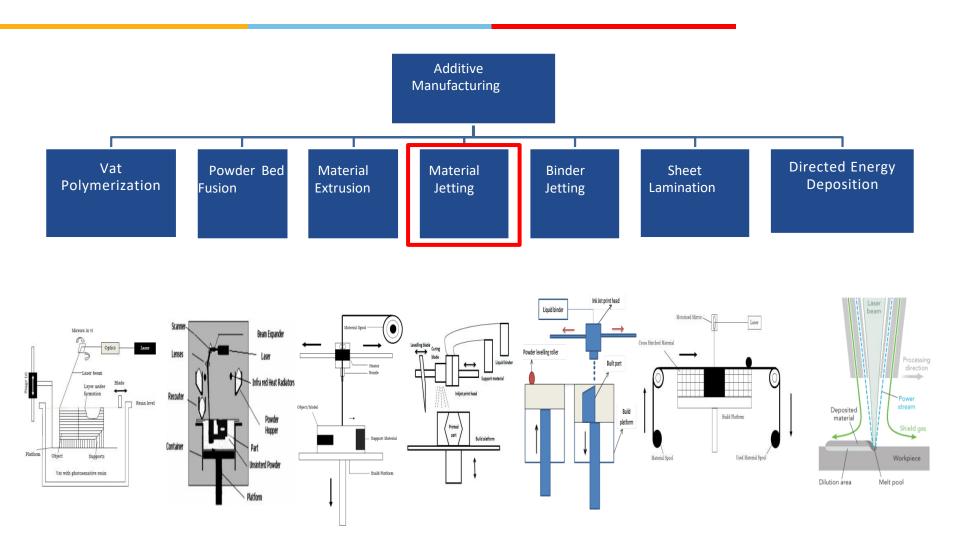


Disadvantages

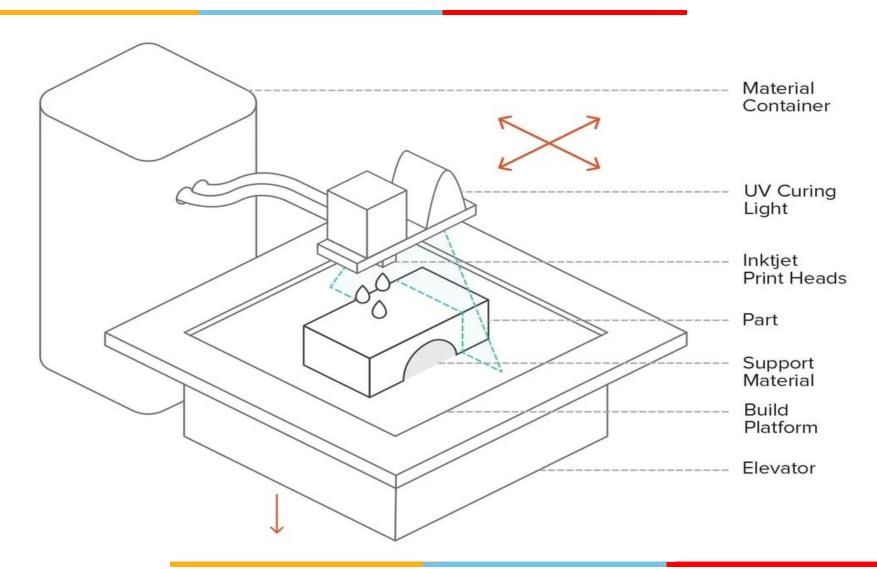
- Visible layer lines
- The extrusion head must continue moving, or else material bumps up
- Supports are required
- Susceptible to warping



ASTM Classification



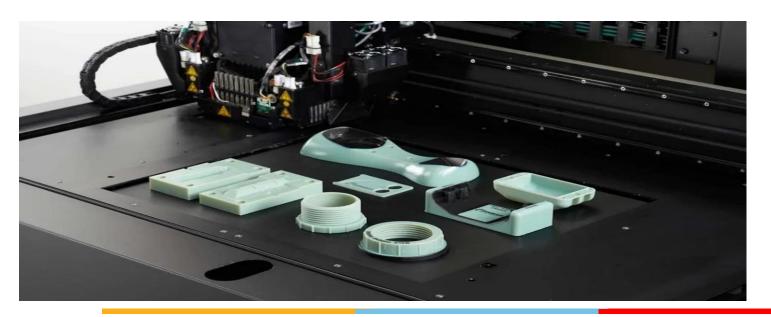
Material Jetting



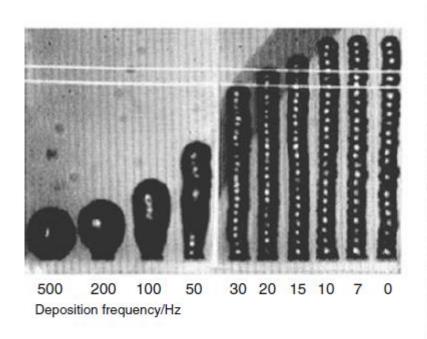


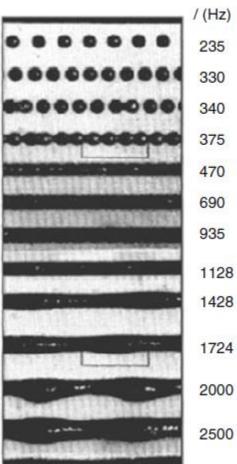
Material Jetting

- Fastest and most accurate 3D printing process
- Build parts using photopolymers and cured using UV lights
- Difference from SLA 3D printer, Jet droplets of photopolymers and cure it using UV light



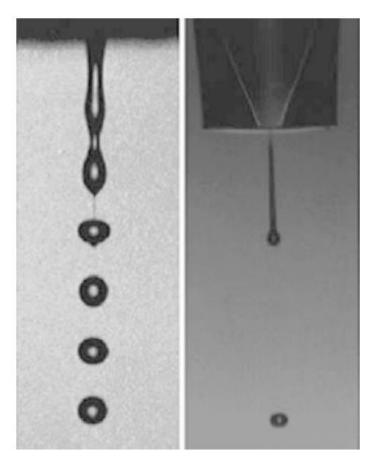
Material Jetting





Droplet formation technologies



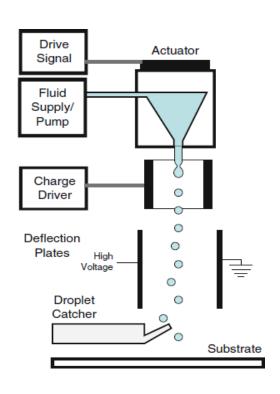


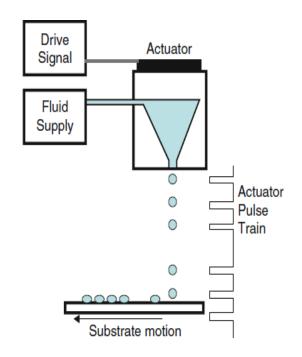
Continuous

Drop-On-Demand

Mechanism of Droplet formation





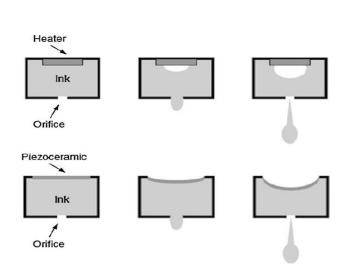


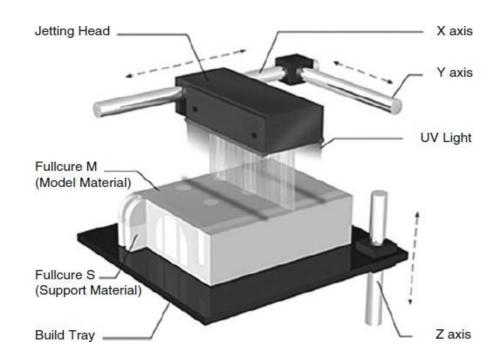
Binary deflection continuous printing

Schematic of drop-on-demand printing system

Thermal (top) and piezoelectric (bottom) DOD ejection

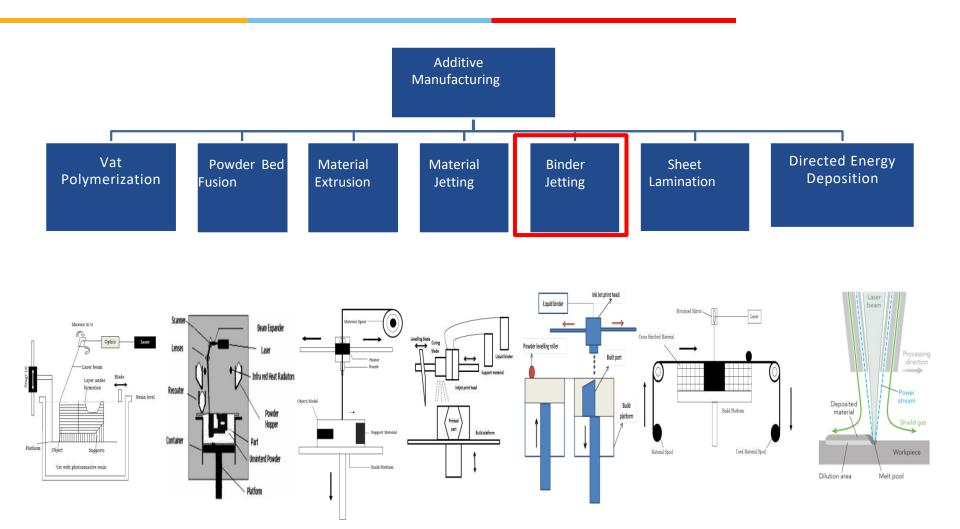




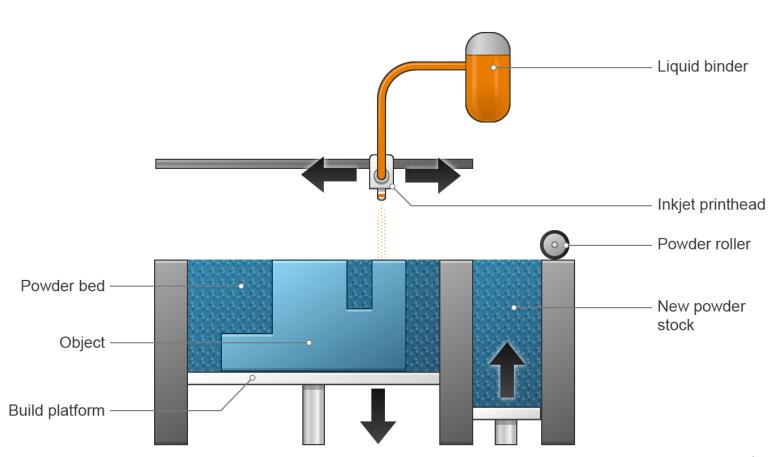


Polyjet build process

ASTM Classification



Binder Jetting



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Binder Jetting



- The binder jetting 3D printing process can work with a variety of materials including metals, sands, and ceramics
- Binder Jetting is unique in that it does not employ heat during the build process.
- For metals an infiltration process is required for improving the mechanical properties of the parts
- Colored parts can be printed







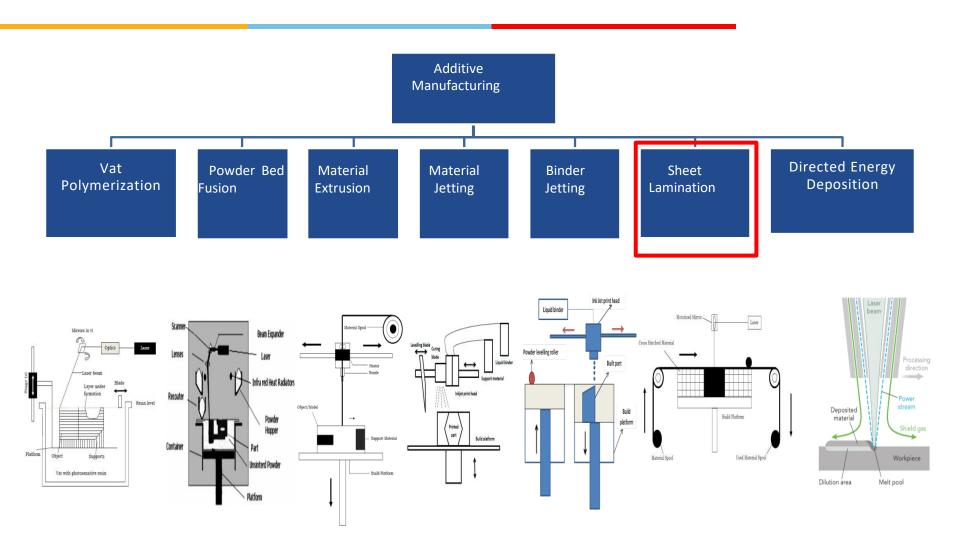
Additional info: https://www.youtube.com/watch?time_continue=253&v=0Q0iHS-9Ti0&feature=emb_logo



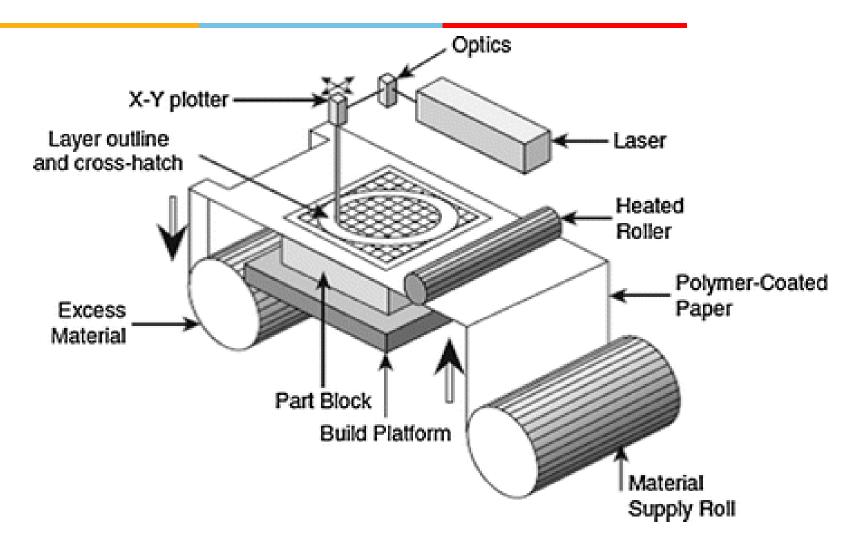
Materials

| Material | Characteristics |
|------------------------------------|--|
| Full Colour Sandstone | Full colour non functional parts Very brittle |
| Silica Sand | Very High Thermal resistance Excellent for sand casting application |
| Stainless steel(bronze infiltered) | Good Mechanical Properties Can be machined ~10% internal porosity |
| Stainless steel(sintered) | Very good mechanical properties High corrosion resistance ~3% internal porosity |
| Inconel alloy (sintered) | Excellent mechanical properties Good temperature resistance High chemical resistance |
| Tungsten carbide (sintered) | Very high hardness Used for the production of cutting tools |

ASTM Classification



Sheet Lamination



Courtesy: lanGibson

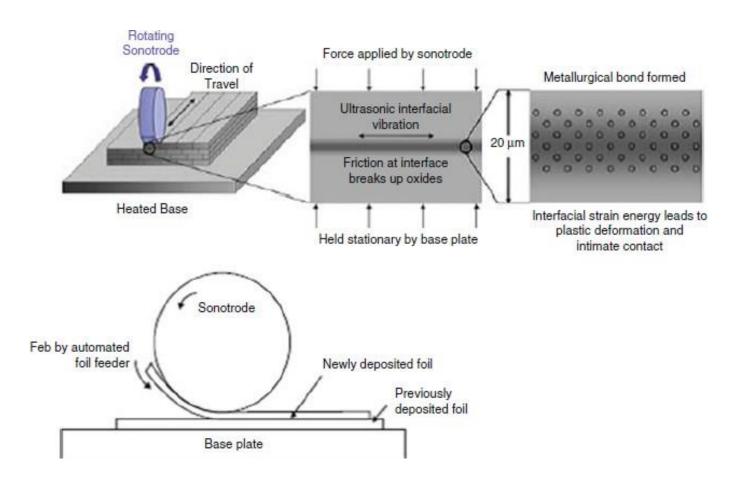


Sheet Lamination Process

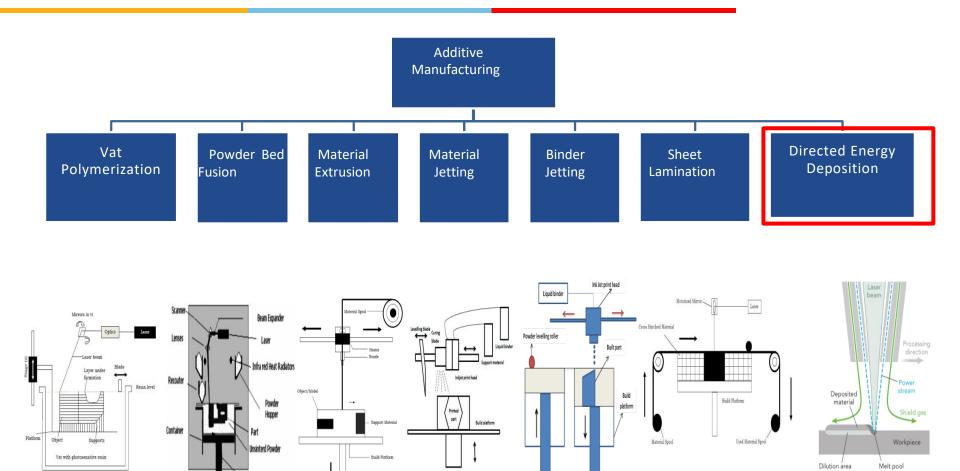
- Composite Based Additive Manufacturing (CBAM) by Impossible Objects Fiber-reinforced composites are fused with a thermoplastic to create very strong parts.
- Selective Lamination Composite Object Manufacturing (SLCOM) by EnvisionTEC. SLCOM uses thermoplastics as a base material and woven fiber composites
- Laminated Object Manufacturing (LOM)
- Selective Deposition Lamination (SDL)
- Ultrasonic Additive Manufacturing (UAM)

Schematic of ultrasonic consolidation

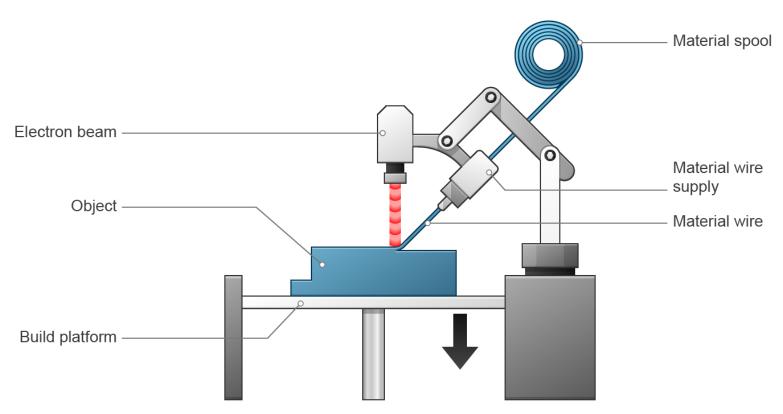




ASTM Classification



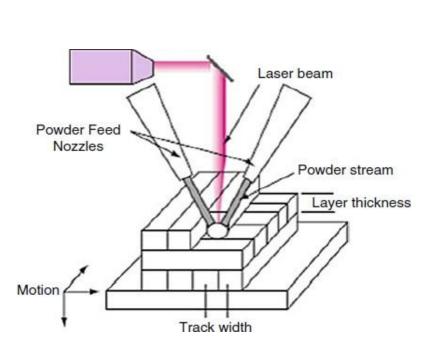
Directed Energy Deposition

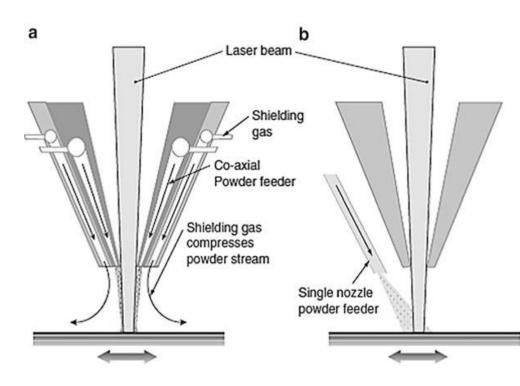


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Schematic of a typical laser powder DED process







- (a) coaxial nozzle feeding and
- (b) Single nozzle feeding



- DED has the ability to produce relatively large parts (build volume > 1000 mm³)
- DED processes can be used to produce components with composition gradients, or hybrid structures consisting of multiple materials having different compositions and structures.





DED



- LENS
- Electron Beam Additive Manufacturing
- Laser deposition Welding and Hybrid manufacturing by DMG Mori

Materials

- For metals, almost any metal that is weldable can be 3D printed with DED.
- Titanium and titanium alloys, Inconel, tantalum, tungsten, niobium, stainless steel, aluminium, etc.

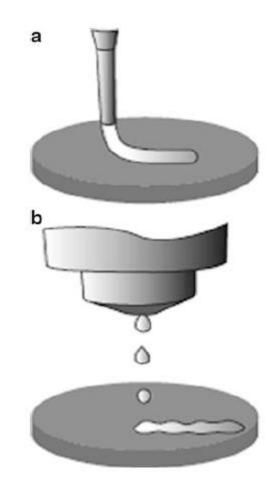
Direct Writing

- Ink based Writing
- Laser Transfer DW
- Thermal Spray DW
- Beam deposition DW
- Liquid Phase direct Deposition



Ink Based Direct Writing

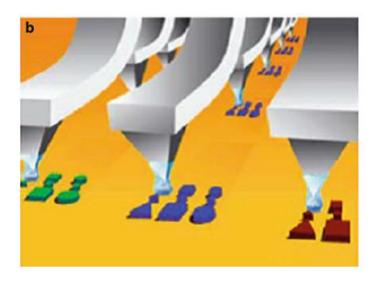
- a) Continuous Filament Writing
- b) Droplet Jetting (courtesy: nScrypt)

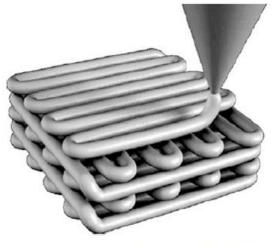


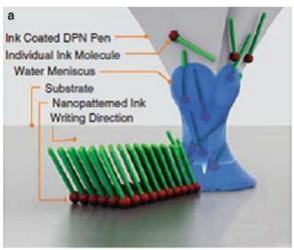
Ink Based DW

innovate achieve lead

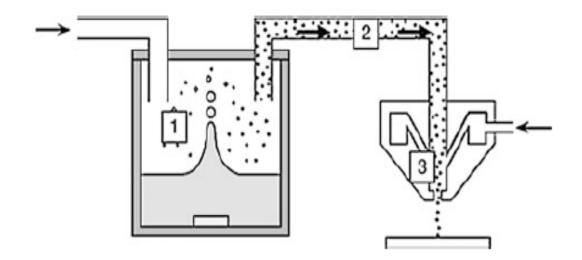
- Nozzle Dispensing
- Quill type process
- Ink Jet printing
- Aerosol DW







Aerosol Jetting



Aerosol Jet System. (1) Liquid material is placed into an atomizer, creating a dense aerosol of tiny droplets 1–5 μm in size. (2) The aerosol is carried by a gas flow to the deposition head (with optional in-flight laser processing). (3) Within the deposition head, the aerosol is focused by a second gas flow and the resulting high-velocity stream is jetted onto the substrate creating features as small as 10 μm in size (Courtesy of Optomec)

Next Session

- Design capabilities of each AM processes
- Opportunistic and Restrictive DfAM

a

Design rules for 3D Printing

Courtesy:3DHubs

| | Supported Walls | Unsupported Walls | Support & Overhangs | Embossed & Engraved Details | Horizontal Bridges | Holes | Connecting /Moving Parts | Escape Holes | Minimum Features | PIn Dlameter | Tolerance |
|------------------------------------|---|---|--|--|---|---|---|--|--|---|---|
| | Walls that are connected to the rest of the print on at least two sides. | Unsupported walls are connected to the rest of the print on less than two sides. | The maximum angle a wall can be printed at without requiring support. | Features on the model that are raised or recessed below the model surface. | The span a technology can print without the need for support. | The minimum diameter a technol- ogy can successfully print a hole. | The recommended clearance between two moving or connecting parts. | The minimum diameter of escape holes to allow for the removal of build material. | The recommended minimum size of a feature to ensure it will not fall to print. | The minimum diameter a pin can be printed at. | The expected tolerance (dimensional accuracy) of a specific technology. |
| | | | | | | | | | | | |
| Fused Deposition Modeling | 0.8 mm | 0.8 mm | 45° | 0.6 mm wide & 2 mm high | 10 mm | Ø2 mm | 0.5 mm | | 2 mm | 3 mm | ±0.5% (lower limit ±0.5 mm) |
| Stereo- Ilthography | 0.5 mm | 1 mm | support always required | 0.4 mm wide & high | | Ø0.5 mm | 0.5 mm | 4 mm | 0.2 mm | 0.5 mm | ±0.5% (lower limit ±0.15 mm) |
| Selective Laser Sintering | 0.7 mm | | | 1 mm wide & high | | Ø1.5 mm | 0.3 mm for moving parts & 0.1 mm for connections | 5 mm | 0.8 mm | 0.8 mm | ±0.3% (lower limit ±0.3 mm) |
| Material Jetting | 1 mm | 1 mm | support always required | 0.5 mm wide & high | | Ø0.5 mm | 0.2 mm | | 0.5 mm | 0.5 mm | ±0.1 mm |
| Binder Jetting | 2 mm | 3 mm | | 0.5 mm wide & high | | Ø1.5 mm | | 5 mm | 2 mm | 2 mm | ±0.2 mm for metal & ±0.3 mm for sand |
| Direct Metal Laser Sintering | 0.4 mm | 0.5 mm | support always required | 0.1 mm wide & high | 2 mm | Ø1.5 mm | | 5 mm | 0.6 mm | 1 mm | ±0.1 mm |





End of Lecture 3-4